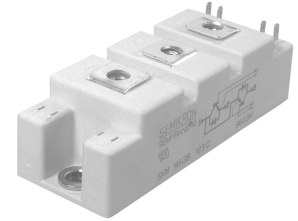


Absolute Maximum Ratings		Values	Units
Symbol	Conditions <sup>1)</sup>		
V <sub>CES</sub>		1700	V
V <sub>CGR</sub>	R <sub>GE</sub> = 20 kΩ	1700	V
I <sub>C</sub>	T <sub>case</sub> = 25/80 °C	110 / 75	A
I <sub>CM</sub>	T <sub>case</sub> = 25/80 °C; t <sub>p</sub> = 1 ms	220 / 150	A
V <sub>GES</sub>		± 20	V
P <sub>tot</sub>	per IGBT, T <sub>case</sub> = 25 °C	625	W
T <sub>j</sub> , (T <sub>stg</sub> )		-40 ... +150 (125)	°C
V <sub>isol</sub>	AC, 1 min.	4000	V
humidity	DIN 40 040	Class F	
climate	DIN IEC 68 T.1	40/125/56	
Inverse Diode <sup>8)</sup>			
I <sub>F</sub> = -I <sub>C</sub>	T <sub>case</sub> = 25/80 °C	80 / 50	A
I <sub>FM</sub> = -I <sub>CM</sub>	T <sub>case</sub> = 25/80 °C; t <sub>p</sub> = 1 ms	200 / 150	A
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.; T <sub>j</sub> = 150 °C	720	A
I <sup>2</sup> t	t <sub>p</sub> = 10 ms; T <sub>j</sub> = 150 °C	2600	A <sup>2</sup> s

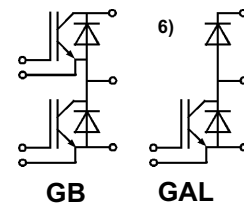
Characteristics		min.	typ.	max.	Units
Symbol	Conditions <sup>1)</sup>				
V <sub>(BR)CES</sub>	V <sub>GE</sub> = 0, I <sub>C</sub> = 1,4 mA	≥ V <sub>CES</sub>	-	-	V
V <sub>GE(th)</sub>	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 6 mA	4,8	5,5	6,2	V
I <sub>CES</sub>	V <sub>GE</sub> = 0 } T <sub>j</sub> = 25 °C	-	0,1	1	mA
	V <sub>CE</sub> = V <sub>CES</sub> } T <sub>j</sub> = 125 °C	-	-	15	mA
I <sub>GES</sub>	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0	-	-	400	nA
V <sub>CESat</sub>	I <sub>C</sub> = 75 A } V <sub>GE</sub> = 15 V;	-	3,4(4,4)	3,9(5)	V
	I <sub>C</sub> = 100 A } T <sub>j</sub> = 25 (125) °C }	-	3,8(5,5)	-	V
g <sub>fs</sub>	V <sub>CE</sub> = 20 V, I <sub>C</sub> = 75 A	27	-	-	S
C <sub>CHC</sub>	per IGBT	-	-	200	pF
C <sub>ies</sub>	V <sub>GE</sub> = 0	-	11	-	nF
C <sub>oes</sub>	V <sub>CE</sub> = 25 V	-	1	-	nF
C <sub>res</sub>	f = 1 MHz	-	0,28	-	nF
L <sub>CE</sub>		-	-	30	nH
t <sub>d(on)</sub>	V <sub>CC</sub> = 1200 V	-	40	-	ns
t <sub>r</sub>	V <sub>GE</sub> = -15 V / +15 V	-	45	-	ns
t <sub>d(off)</sub>	I <sub>C</sub> = 75 A, ind. load	-	400	-	ns
t <sub>f</sub>	R <sub>Gon</sub> = R <sub>Goff</sub> = 10 Ω	-	56	-	ns
E <sub>on</sub>	T <sub>j</sub> = 125 °C	-	35	-	mWs
E <sub>off</sub>		-	21	-	mWs
Inverse Diode <sup>8)</sup>					
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 75 A } V <sub>GE</sub> = 0 V;	-	2,2(2,0)	2,7(2,3)	V
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 100 A } T <sub>j</sub> = 25 (125) °C }	-	2,45(2,25)	-	V
V <sub>TO</sub>	T <sub>j</sub> = 125 °C	-	1,3	1,5	V
r <sub>t</sub>	T <sub>j</sub> = 125 °C	-	9	13	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 75 A; T <sub>j</sub> = 25 (125) °C <sup>2)</sup>	-	38(51)	-	A
Q <sub>rr</sub>	I <sub>F</sub> = 75 A; T <sub>j</sub> = 25 (125) °C <sup>2)</sup>	-	8(19)	-	μC
FWD of type "GAL" <sup>6) 8)</sup>					
V <sub>F</sub> = V <sub>EC</sub>	I <sub>F</sub> = 100 A } V <sub>GE</sub> = 0 V;	-	2,2(1,9)	2,7(2,4)	V
V <sub>TO</sub>	T <sub>j</sub> = 125 °C	-	1,2	1,5	V
r <sub>t</sub>	T <sub>j</sub> = 125 °C	-	7	9	mΩ
t <sub>rr</sub>	I <sub>F</sub> = 100 A; T <sub>j</sub> = 25 (125) °C <sup>2)</sup>	-	50(70)	-	μs
Q <sub>rr</sub>	I <sub>F</sub> = 100 A; T <sub>j</sub> = 25 (125) °C <sup>2)</sup>	-	10(27)	-	μC
Thermal characteristics					
R <sub>thjc</sub>	per IGBT	-	-	0,2	°C/W
R <sub>thjc</sub>	per diode / FWD "GAL"	-	-	0,63/0,4	°C/W
R <sub>thch</sub>	per module	-	-	0,05	°C/W

## SEMITRANS® M IGBT Modules

### SKM 100 GB 173 D SKM 100 GAL 173 D <sup>6)</sup>



### SEMITRANS 2



### Features

- N channel, Homogeneous Si
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 \* I<sub>Cnom</sub>
- Latch-up free
- Fast & soft inverse CAL diodes <sup>8)</sup>
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (10 mm) and creepage distances (20 mm)

### Typical Applications

- AC inverter driveson mains 575 - 750 V<sub>AC</sub>
- DC bus voltage 750 - 1200 V<sub>DC</sub>
- Public transport (auxiliary syst.)
- Switching (not for linear use)

<sup>1)</sup> T<sub>case</sub> = 25 °C, unless otherwise specified

<sup>2)</sup> I<sub>F</sub> = -I<sub>C</sub>, V<sub>R</sub> = 1200 V, -di<sub>F</sub>/dt = 800 A/μs, V<sub>GE</sub> = 0 V

<sup>6)</sup> The free-wheeling diode of the GAL type has the data of the inverse diode of SKM 150 GB 173 D

<sup>8)</sup> CAL = Controlled Axial Lifetime Technology

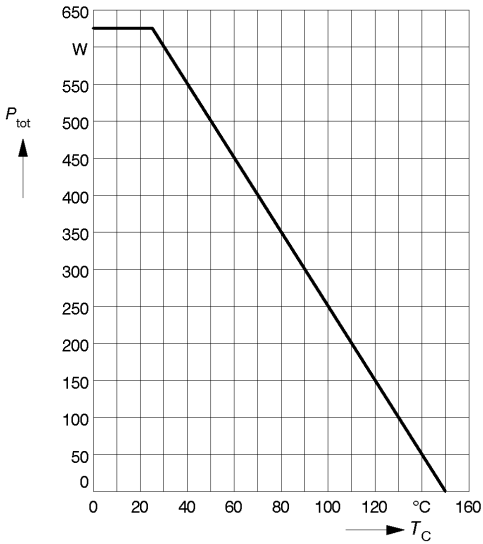


Fig. 1 Rated power dissipation  $P_{tot} = f(T_C)$

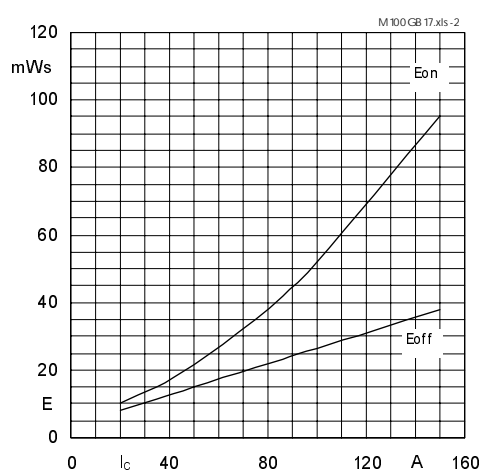


Fig. 2 Turn-on /-off energy  $= f(I_C)$

$T_J = 125\text{ °C}$   
 $V_{CE} = 1200\text{ V}$   
 $V_{GE} = \pm 15\text{ V}$   
 $R_G = 10\text{ }\Omega$

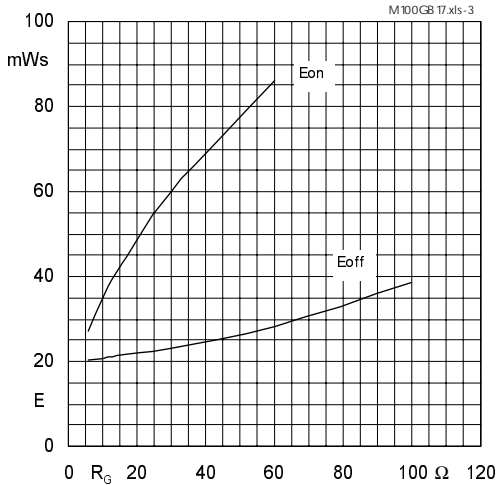


Fig. 3 Turn-on /-off energy  $= f(R_G)$

$T_J = 125\text{ °C}$   
 $V_{CE} = 1200\text{ V}$   
 $V_{GE} = \pm 15\text{ V}$   
 $I_C = 75\text{ A}$

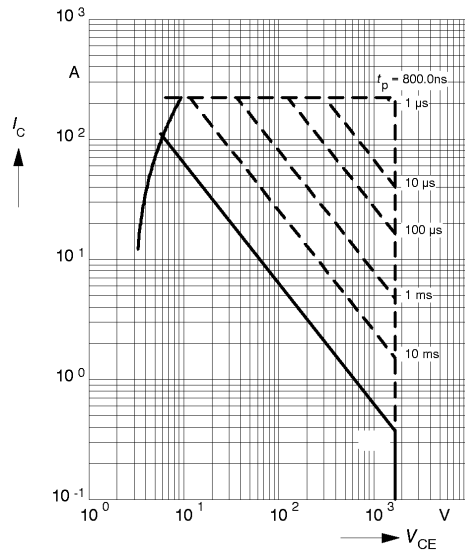


Fig. 4 Maximum safe operating area (SOA)  $I_C = f(V_{CE})$

1 pulse  
 $T_C = 25\text{ °C}$   
 $T_J \leq 150\text{ °C}$

Not recommended for linear duty

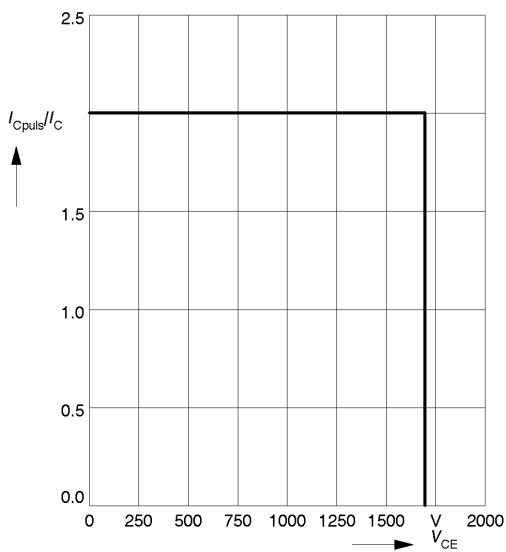


Fig. 5 Turn-off safe operating area (RBSOA)

$T_J \leq 150\text{ °C}$   
 $V_{GE} = \pm 15\text{ V}$   
 $R_{Goff} = 10\text{ }\Omega$   
 $I_C = 75\text{ A}$

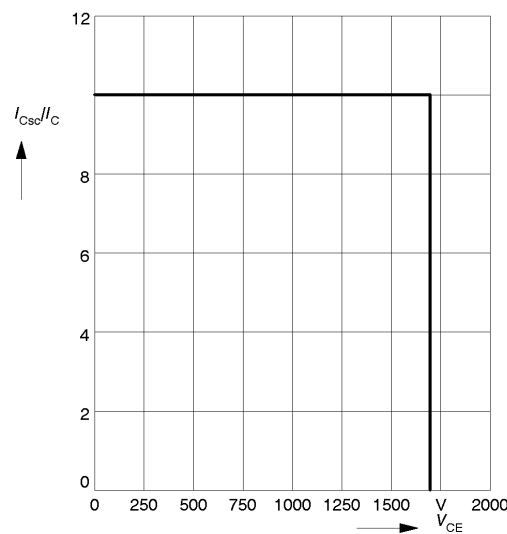


Fig. 6 Safe operating area at short circuit  $I_C = f(V_{CE})$

$T_J \leq 150\text{ °C}$   
 $V_{GE} = \pm 15\text{ V}$   
 $t_{sc} \leq 10\text{ }\mu\text{s}$   
 $L_{ext} < 50\text{ nH}$   
 $I_C = 75\text{ A}$

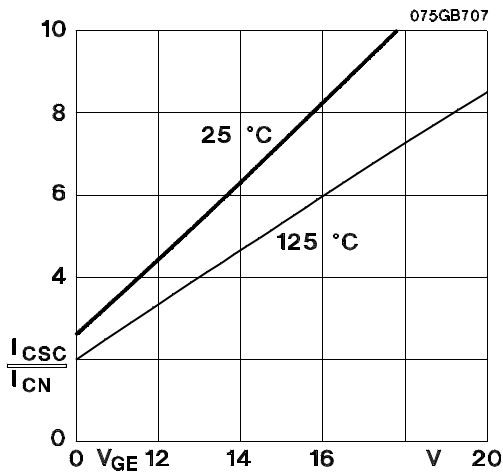


Fig. 7 Short circuit current vs. turn-on gate voltage

$V_C = 1200 \text{ V}$   
 $I_C = I_{CN} = 75 \text{ A}$   
 $t_p = 10 \mu\text{s}$   
 $L_{\text{ext}} \leq 25 \text{ nH}$   
 $R_{\text{Gon}} = 10 \Omega$   
 $R_{\text{Goff}} = 10 \Omega$

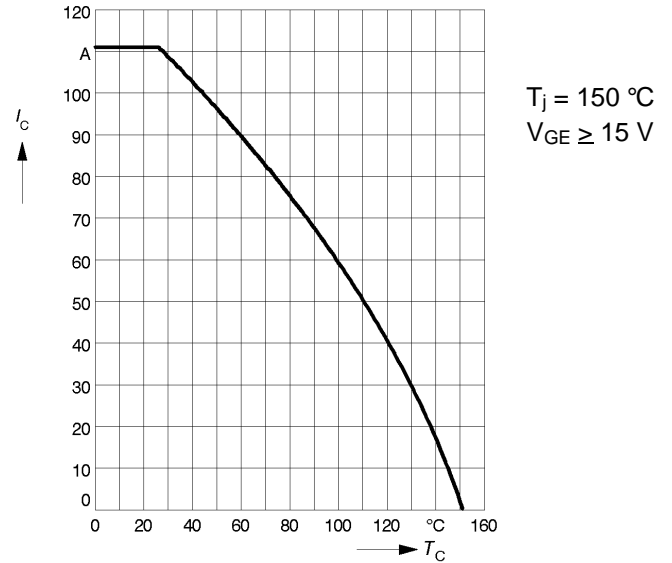


Fig. 8 Rated current vs. temperature  $I_C = f(T_C)$

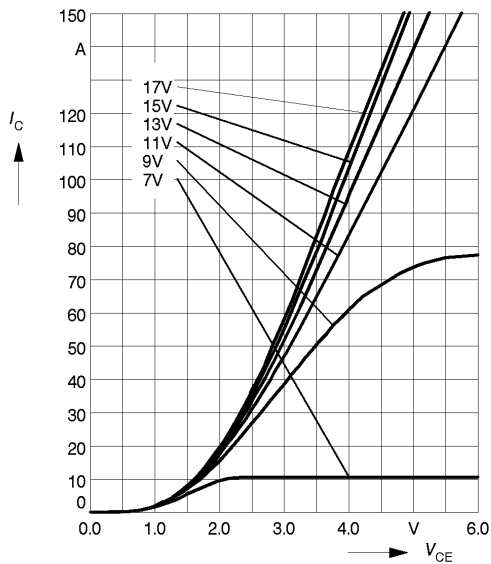


Fig. 9 Typ. output characteristic,  $t_p = 80 \mu\text{s}$ ;  $T_j = 25 \text{ °C}$

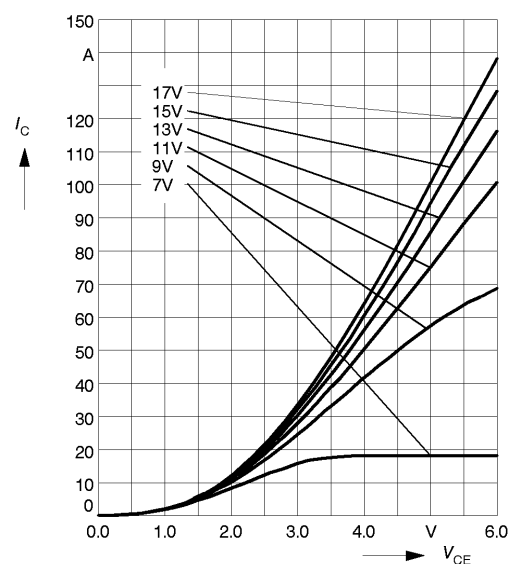


Fig. 10 Typ. output characteristic,  $t_p = 80 \mu\text{s}$ ;  $T_j = 125 \text{ °C}$

$$P_{\text{cond}(t)} = V_{\text{CEsat}(t)} \cdot I_C(t)$$

$$V_{\text{CEsat}(t)} = V_{\text{CE(To)(Tj)}} + r_{\text{CE}(Tj)} \cdot I_C(t)$$

$$V_{\text{CE(To)(Tj)}} \leq 1,9 + 0,003 (T_j - 25) \text{ [V]}$$

$$r_{\text{CE}(Tj)} = 0,023 + 0,00007 (T_j - 25) \text{ [\Omega]}$$

valid for  $V_{\text{GE}} = +15 \frac{+2}{-1} \text{ [V]}$ ;  $I_C > 0,3 I_{\text{Cnom}}$

Fig. 11 Typ. saturation characteristic (IGBT)  
Calculation elements and equations

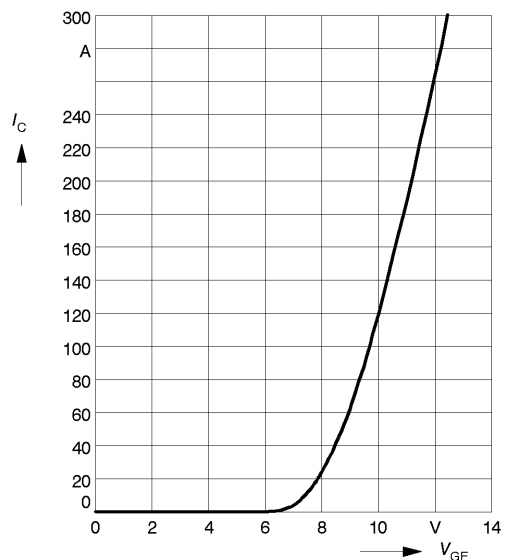


Fig. 12 Typ. transfer characteristic,  $t_p = 80 \mu\text{s}$ ;  $V_{\text{CE}} = 20 \text{ V}$

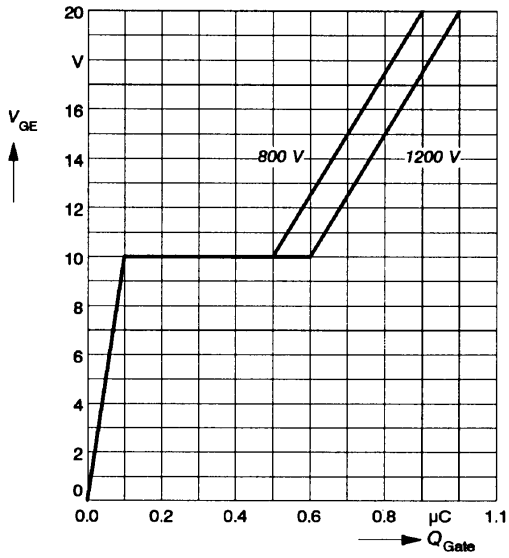


Fig. 13 Typ. gate charge characteristic

$I_{Cpuls} = 75 \text{ A}$

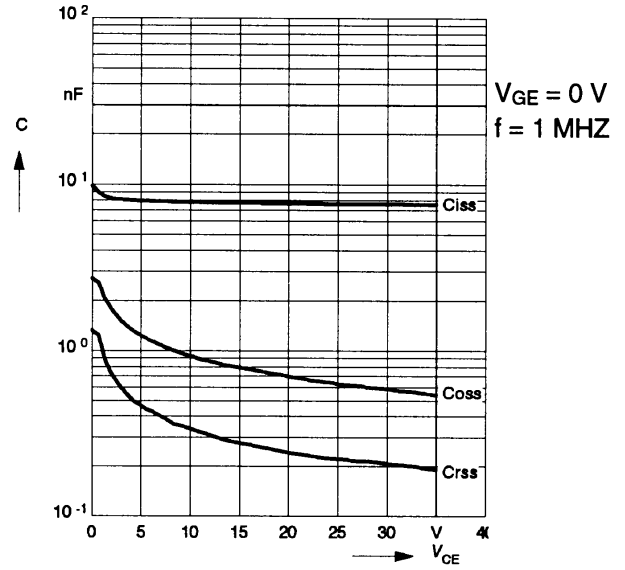


Fig. 14 Typ. capacitances vs.  $V_{CE}$

$V_{GE} = 0 \text{ V}$   
 $f = 1 \text{ MHz}$

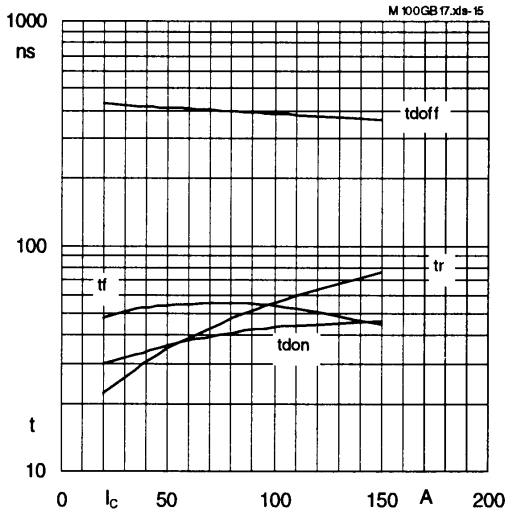


Fig. 15 Typ. switching times vs.  $I_c$

$T_j = 125 \text{ }^\circ\text{C}$   
 $V_{CE} = 1200 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $R_G = 10 \text{ } \Omega$   
ind. load

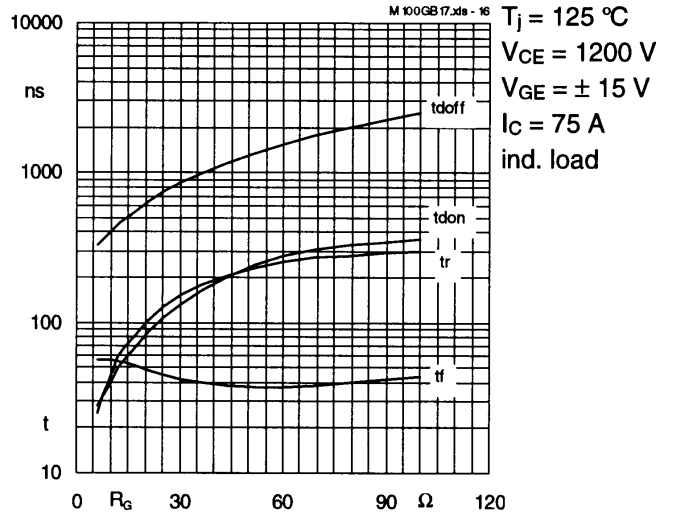


Fig. 16 Typ. switching times vs.  $R_G$

$T_j = 125 \text{ }^\circ\text{C}$   
 $V_{CE} = 1200 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $I_c = 75 \text{ A}$   
ind. load

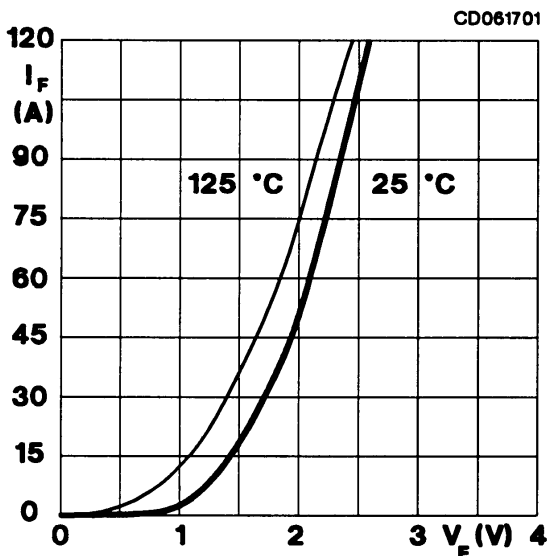


Fig. 17 Typ. CAL diode forward characteristic

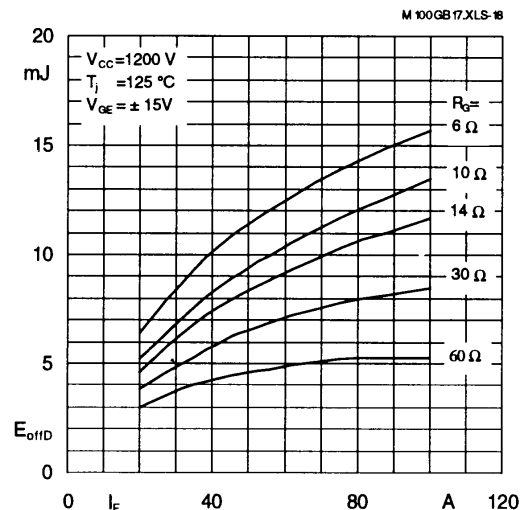


Fig. 18 Typ. Diode turn-off energy dissipation per pulse

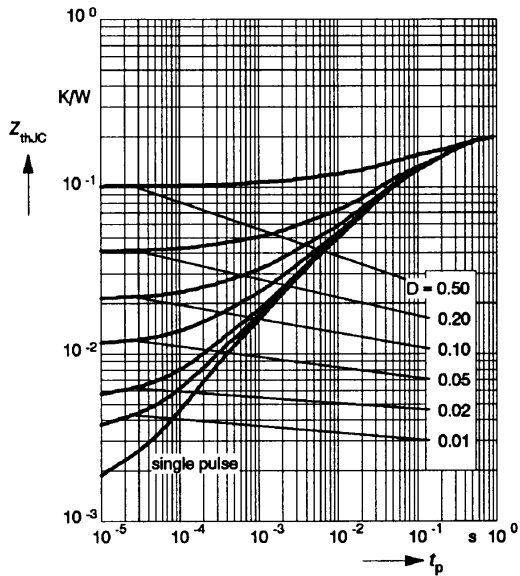


Fig. 19 Transient thermal impedance of IGBT:  $Z_{thjC} = f(t_p)$ ;  $D = t_p / t_c = t_p \cdot f$

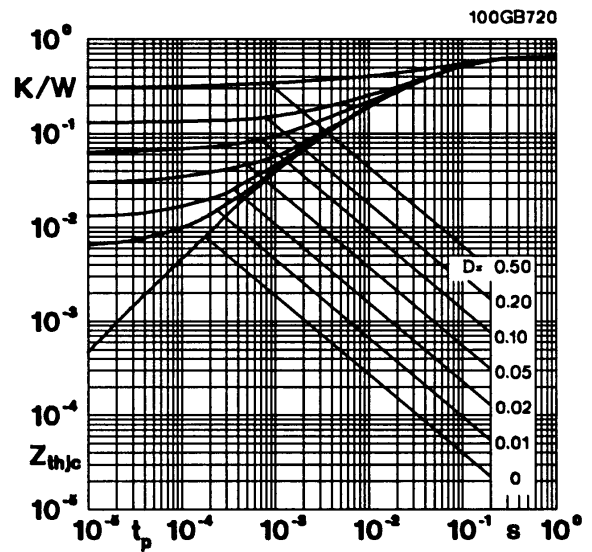


Fig. 20 Transient thermal impedance of inverse diode:  $Z_{thjC} = f(t_p)$

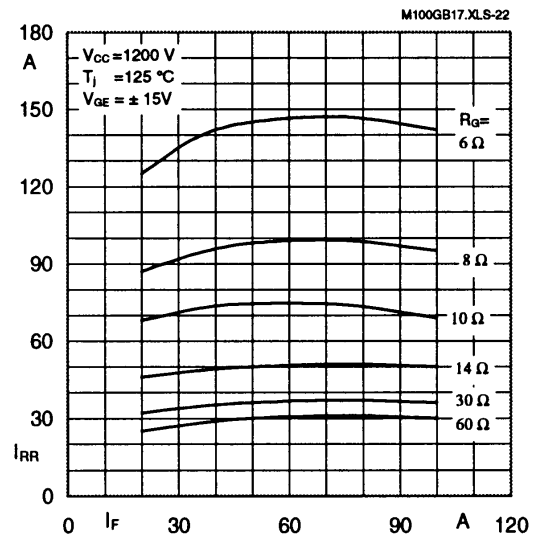


Fig. 22 Typ. CAL diode peak reverse recovery current  $I_{RR} = f(I_F; R_G)$

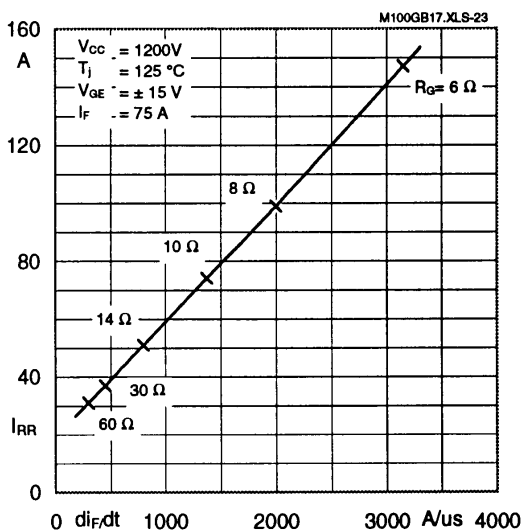


Fig. 23 Typ. CAL diode peak reverse recovery current  $I_{RR} = f(di/dt)$

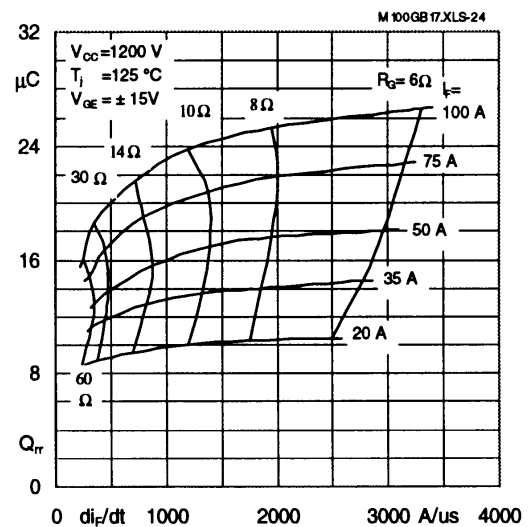


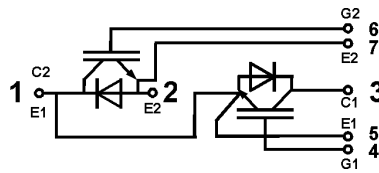
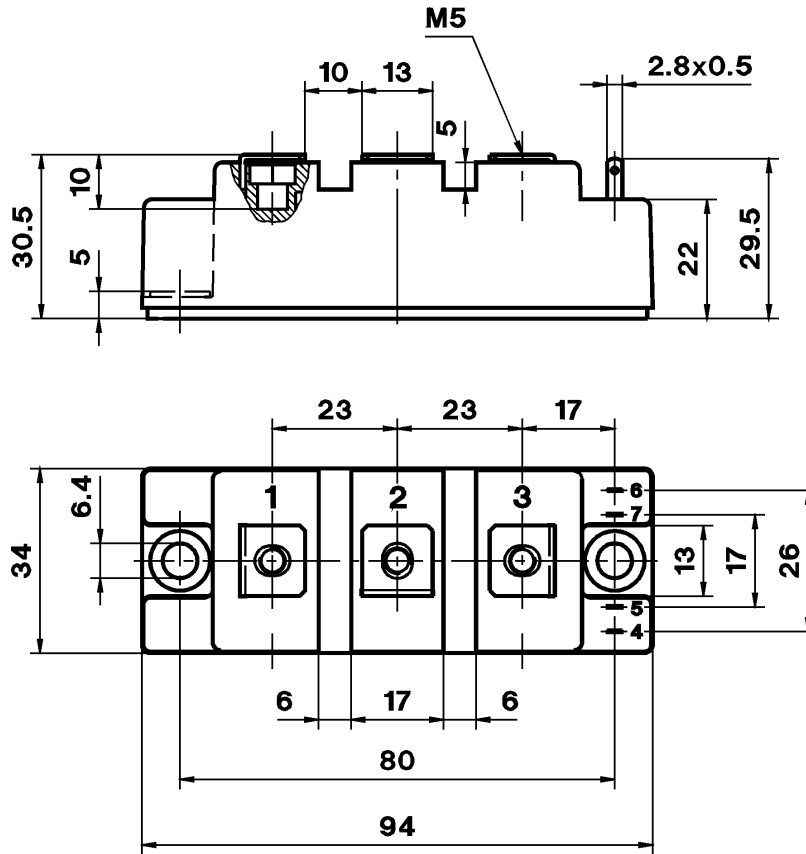
Fig. 24 Typ. CAL diode recovered charge  $Q_{rr}$

**SEMITRANS 2**

Case D 61  
 UL Recognized  
 File no. E 63 532

CASED61

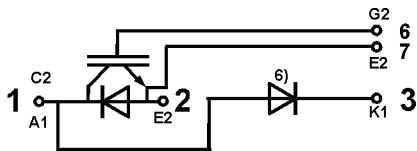
**SKM 100 GB 173 D**



Dimensions in mm

**SKM 100 GAL 173 D**

Case D 62 ( → D 61)



Case outline and circuit diagram

Mechanical Data			Values			Units
Symbol	Conditions		min.	typ.	max.	
M <sub>1</sub>	to heatsink, SI Units to heatsink, US Units	(M6)	3 27	—	5 44	Nm lb.in.
M <sub>2</sub>	for terminals, SI Units for terminals, US Units	(M5)	2,5 22	—	5 44	Nm lb.in.
a			—	—	5x9,81	m/s <sup>2</sup>
w			—	—	160	g

**This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.**

Eight devices are supplied in one SEMIBOX A without mounting hardware, which can be ordered separately under Ident No. 33321100 (for 10 SEMITRANS 2)

Larger packing units of 20 or 42 pieces are used if suitable

<sup>6)</sup> Freewheeling diode → page B 6 – 47, remark 6.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.